

# Pre-Aligners **mPA**



## Description

The pre-aligner provides alignment for 150 mm (6") up to 300 mm (12") wafers. It aligns the wafer and finds the precise orientation of its notch or flat. Through "vacuum handshake" between end-effector and pre-aligner the wafer is always secure with a minimal touch at the wafer back side. Several mechatronic end-effectors can be used for loading and unloading.

## Optional features

- OCR reader for wafer ID
- eWLB wafer handling

## Common specifications

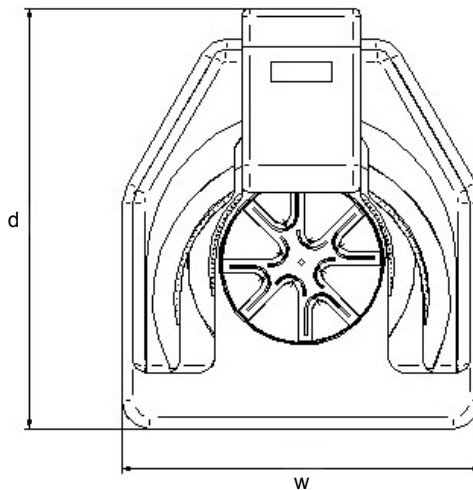
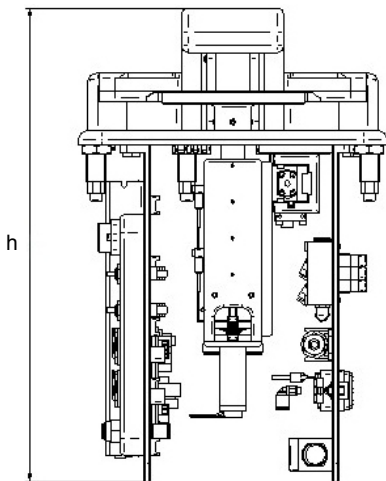
Wafer thickness	> 50 µm (1,97 mil)
Wafer recognition	Via digital vacuum sensors
Cleanroom class (ISO EN 14 644-1)	ISO class 4
Centering accuracy (X,Y axis)	Up to 0.05 mm
Alignment accuracy flat/notch	Up to 0.1°
Alignment sensor	Laser class 2
<b>Pneumatic</b>	
Pneumatic media	CDA or N <sub>2</sub>
Supply pressure	5.5 bar – 6.5 bar
<b>Electrical engineering</b>	
Power supply	24 VDC
Power consumption	Max. 140 W
Fuse	T6A
<b>Interface</b>	
Interface	CAN open

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# Pre-Aligners **mPA**

## Specifications

Pre-aligner	mPA 150/200	mPA 200/300
Wafer size	150 mm (6") and 200 mm (8")	200 mm (8") and 300 mm (12")
Weight	12.4 kg	n.a. - special customization  Details on request
Cycle time per wafer	15 sec.	
<b>Working space</b>		
X axis	35 mm	
Z axis	40 mm	
Theta axis	$\infty$	
<b>Pneumatic</b>		
CDA / N2 supply	5.5 – 6.5 bar	



Dimensions in mm (w/d/h): 256 x 300 x 391

**ASK FOR YOUR CUSTOMIZED SOLUTION!**

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